XP04286

Silicon NPN epitaxial planar type (Tr1) Silicon PNP epitaxial planar type (Tr2)

For switching/digital circuits

Features

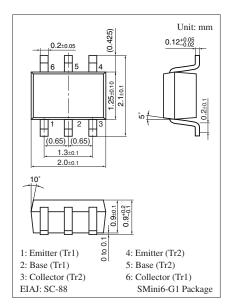
- Two elements incorporated into one package (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

Basic Part Number

• UNR221N + UNR2119

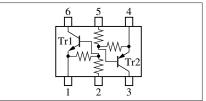
Absolute Maximum Ratings $T_a = 25^{\circ}C$

	Parameter	Symbol	Rating	Unit
Tr1	Collector-base voltage (Emitter open)	V _{CBO}	50	V
	Collector-emitter voltage (Base open)	V _{CEO}	50	V
	Collector current	I _C	100	mA
Tr2	Collector-base voltage (Emitter open)	V _{CBO}	-50	V
	Collector-emitter voltage (Base open)	V _{CEO}	-50	V
	Collector current	I _C	-100	mA
Overall	Total power dissipation	P _T	150	mW
	Junction temperature	Tj	150	°C
	Storage temperature	T _{stg}	-55 to +150	°C



Marking Symbol: HO

Internal Connection



\blacksquare Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

• Tr1

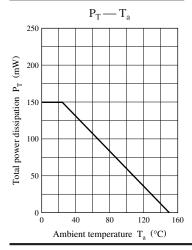
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu A, \ I_{\rm E} = 0$	50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$	50			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 50 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 50 \text{ V}, I_B = 0$			0.5	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 6 V, I_C = 0$			0.2	mA
Forward current transfer ratio	h _{FE}	$V_{CE} = 10 \text{ V}, \text{ I}_{C} = 5 \text{ mA}$	80		400	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0.3 \text{ mA}$			0.25	V
Output voltage high-level	V _{OH}	$V_{CC} = 5 \text{ V}, V_{B} = 0.5 \text{ V}, \text{R}_{L} = 1 \text{k}\Omega$	4.9			V
Output voltage low-level	V _{OL}	$V_{CC} = 5 \text{ V}, V_B = 2.5 \text{ V}, R_L = 1 k\Omega$			0.2	V
Input resistance	R ₁		-30%	4.7	+30%	kΩ
Resistance ratio	R ₁ / R ₂			0.1		
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$		150		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. • Tr2

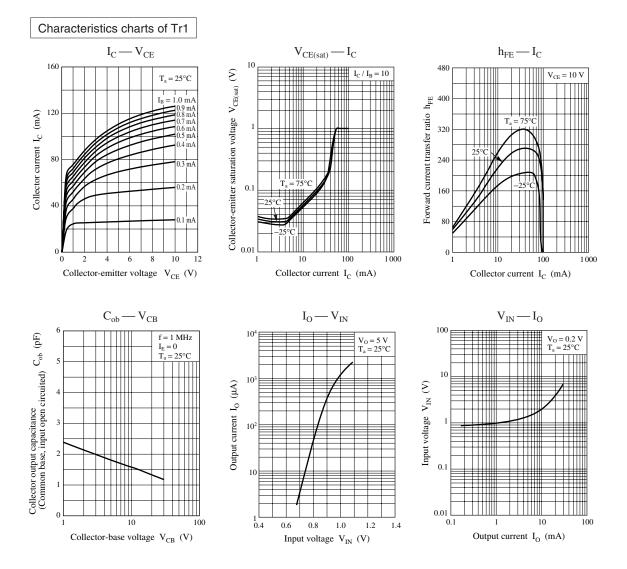
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu {\rm A}, \ I_{\rm E} = 0$	-50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = -50 \text{ V}, I_E = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -50 \text{ V}, I_B = 0$			- 0.5	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = -6 V, I_C = 0$			-1.5	mA
Forward current transfer ratio	h _{FE}	$V_{CE} = -10 \text{ V}, I_C = -5 \text{ mA}$	30			—
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -10$ mA, $I_{\rm B} = -0.3$ mA			- 0.25	V
Output voltage high-level	V _{OH}	$V_{CC} = -5 \text{ V}, V_B = -0.5 \text{ V}, R_L = 1 \text{ k}\Omega$	-4.9			V
Output voltage low-level	V _{OL}	$V_{CC} = -5 \text{ V}, V_B = -2.5 \text{ V}, R_L = 1 \text{ k}\Omega$			- 0.2	V
Input resistance	R ₁		-30%	1	+30%	kΩ
Resistance ratio	R ₁ / R ₂			0.1		
Transition frequency	f _T	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

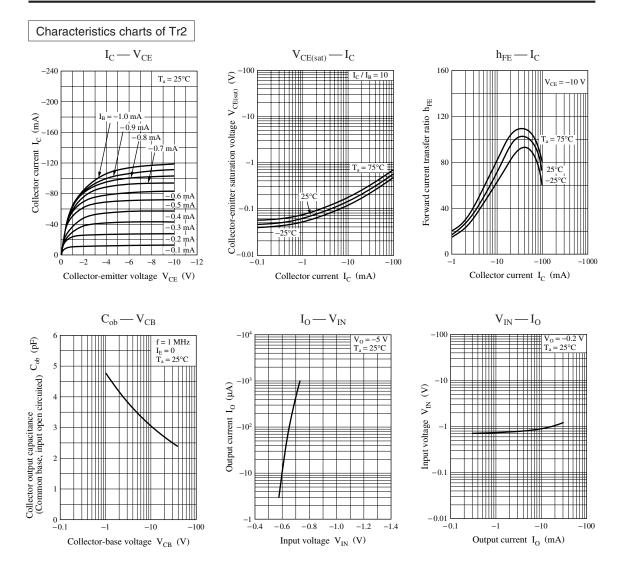
Common characteristics chart



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